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Datasheet

## General Purpose CMOS Logic IC

# Automotive Single Buffer

## BD7LS34G-C

### General Description

The BD7LS34G-C is a Single Buffer and qualified for automotive applications. This is designed for 1.65 V to 5.5 V power supply voltage operation.
When it is power down, the Output Tolerant circuit protects the output circuit from the back flow current through the connected system.

### Features

- AEC-Q100 Qualified*(Note 1)*
  - 4000 V Human-body Model
  - 1000 V Charged-device Model
- Low Power Consumption
- 5.5 V Tolerant Inputs
- Output Tolerant Supports Partial Power Down Mode Operation
- Package SSOP5 is Similar to SOT-23-5(JEDEC)

*(Note 1)* Grade 1

### Applications

- Automotive

### Key Specifications

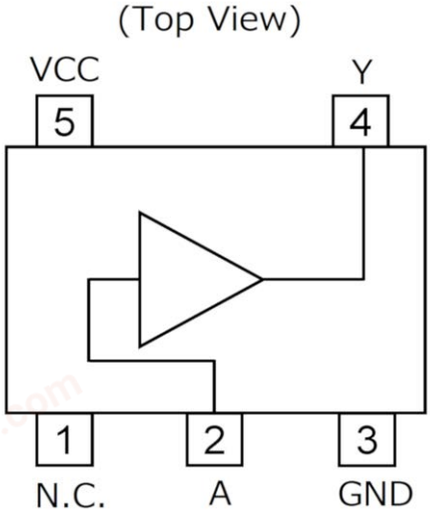
- Supply Voltage Range: 1.65 V to 5.5 V
- Low Current Consumption ($I_{CC}$): 10 µA (Max)
- Operating Temperature Range: -40 °C to +125 °C
- Max Propagation Delay Time: 11.0 ns (@3.0 V)
- Output Drive Capability: ±24 mA (@3.0 V)

| Package | W(Typ) x D (Typ) x H (Max) |
|---|---|
| SSOP5 | 2.9 mm x 2.8 mm x 1.25 mm |




SSOP5

### Pin Configuration and Logic Diagram




### Pin Descriptions

| Pin No. | Pin Name | Function | I/O |
|---|---|---|---|
| 1 | N.C. | No connection | - |
| 2 | A | Input | I |
| 3 | GND | Ground | - |
| 4 | Y | Output | O |
| 5 | VCC | Power supply | - |

### Truth Table

| Input A | Output Y |
|---|---|
| L | L |
| H | H |

○Product structure : Silicon integrated circuit ○This product has no designed protection against radioactive rays


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## Absolute Maximum Ratings (Ta = 25 °C)

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Supply Voltage Range | $V_{CC}$ | -0.5 to +6.5 | V |
| Input Voltage Range | $V_{IN}$ | -0.5 to +6.5 | V |
| Input Diode Current ($V_{IN}$ < 0) | $I_{IK}$ | -50 | mA |
| Output Diode Current ($V_O$ < 0) | $I_{OK}$ | -50 | mA |
| Output Current | $I_O$ | ±50 | mA |
| VCC-GND Current | $I_{CC}$ | ±50 | mA |
| Maximum Junction Temperature | Tjmax | +150 | °C |
| Storage Temperature Range | Tstg | -55 to +150 | °C |

***Caution 1:*** *Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.*

***Caution 2:*** *Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.*

## Thermal Resistance *(Note 1)*

| Parameter | Symbol | Thermal Resistance (Typ) | | Unit |
|---|---|---|---|---|
| | | 1s*(Note 3)* | 2s2p*(Note 4)* | |
| SSOP5 | | | | |
| Junction to Ambient | $\theta_{JA}$ | 376.5 | 185.4 | °C/W |
| Junction to Top Characterization Parameter*(Note 2)* | $\Psi_{JT}$ | 40 | 30 | °C/W |

| Layer Number of Measurement Board | Material | Board Size |
|---|---|---|
| Single | FR-4 | 114.3 mm x 76.2 mm x 1.57 mmt |

| Top | |
|---|---|
| Copper Pattern | Thickness |
| Footprints and Traces | 70 µm |

| Layer Number of Measurement Board | Material | Board Size |
|---|---|---|
| 4 Layers | FR-4 | 114.3 mm x 76.2 mm x 1.6 mmt |

| Top | | 2 Internal Layers | | Bottom | |
|---|---|---|---|---|---|
| Copper Pattern | Thickness | Copper Pattern | Thickness | Copper Pattern | Thickness |
| Footprints and Traces | 70 µm | 74.2 mm x 74.2 mm | 35 µm | 74.2 mm x 74.2 mm | 70 µm |

*(Note 1)* Based on JESD51-2A (Still-Air).
*(Note 2)* The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.
*(Note 3)* Using a PCB board based on JESD51-3.
*(Note 4)* Using a PCB board based on JESD51-7.

## Recommended Operating Conditions

| Parameter | Symbol | Min | Typ | Max | Unit | Conditions |
|---|---|---|---|---|---|---|
| Supply Voltage | $V_{CC}$ | 1.65 | - | 5.5 | V | Operating |
| | | 1.5 | - | 5.5 | V | Data Retention Only |
| Input Voltage | $V_{IN}$ | 0 | - | 5.5 | V | - |
| Output Voltage | $V_O$ | 0 | - | $V_{CC}$ | V | - |
| Input Transition Rise or Fall Rate | Δt/Δv | - | - | 20 | ns/V | $V_{CC}$ = 1.65 V to 1.95 V |
| | | | | | | $V_{CC}$ = 2.3 V to 2.7 V |
| | | - | - | 10 | | $V_{CC}$ = 3.0 V to 3.6 V |
| | | - | - | 5 | | $V_{CC}$ = 4.5 V to 5.5 V |
| Operating Temperature | Topr | -40 | - | +125 | °C | - |

*(Note)* The recommended operating conditions are the range where operation is guaranteed. If this ranges are exceeded, operation is not guaranteed even within the absolute maximum ratings. Unused inputs must be tied to either $V_{CC}$ or GND.


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## Electrical Characteristics

**(Unless otherwise specified $V_{CC}$ = 1.65 V to 5.5 V and Ta = -40 °C to +125 °C)**

| Parameter | Symbol | Min | Typ | Max | Unit | Conditions | |
|---|---|---|---|---|---|---|---|
| | | | | | | $V_{CC}$ | |
| Input “H” Voltage | $V_{IH}$ | $V_{CC}$ × 0.7 | - | - | V | 1.65 V to 5.5 V | - |
| Input “L” Voltage | $V_{IL}$ | - | - | $V_{CC}$ × 0.3 | V | 1.65 V to 5.5 V | - |
| Output “H” Voltage | $V_{OH}$ | $V_{CC}$ - 0.1 | - | - | V | 1.65 V to 5.5 V | $I_{OH}$ = -100 µA |
| | | 1.2 | - | - | | 1.65 V | $I_{OH}$ = -4 mA |
| | | 1.8 | - | - | | 2.3 V | $I_{OH}$ = -8 mA |
| | | 2.3 | - | - | | 3.0 V | $I_{OH}$ = -16 mA |
| | | 2.1 | - | - | | 3.0 V | $I_{OH}$ = -24 mA |
| | | 3.4 | - | - | | 4.5 V | $I_{OH}$ = -32 mA |
| Output “L” Voltage | $V_{OL}$ | - | - | 0.10 | V | 1.65 V to 5.5 V | $I_{OL}$ = 100 µA |
| | | - | - | 0.45 | | 1.65 V | $I_{OL}$ = 4 mA |
| | | - | - | 0.40 | | 2.3 V | $I_{OL}$ = 8 mA |
| | | - | - | 0.60 | | 3.0 V | $I_{OL}$ = 16 mA |
| | | - | - | 0.90 | | 3.0 V | $I_{OL}$ = 24 mA |
| | | - | - | 1.00 | | 4.5 V | $I_{OL}$ = 32 mA |
| Input Current | $I_{IN}$ | - | - | ±2 | µA | 0 V to 5.5 V | $V_{IN}$ = 5.5 V or GND |
| Power Off Output Pin Current | $I_{OFF}$ | - | - | 10 | µA | 0 V | $V_{IN}$ or $V_O$ = 5.5 V |
| Quiescent Supply Current | $I_{CC}$ | - | - | 10 | µA | 1.65 V to 5.5 V | - |
| Supply Current Increase | $\Delta I_{CC}$ | - | - | 600 | µA | 3.0 V to 5.5 V | Input: $V_{CC}$ - 0.6 V |
| Input Capacitance | $C_I$ | - | 4 | - | pF | 3.3 V | $V_{IN}$ = $V_{CC}$ or GND Ta = 25 °C |


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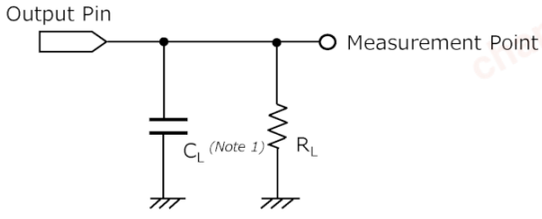
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## Switching Characteristics
**(Unless otherwise specified $V_{CC}$ = 1.65 V to 5.5 V and Ta = -40 °C to +125 °C)**

| Parameter | Symbol | FROM (Input) | TO (Output) | Min | Typ | Max | Unit | Conditions | |
|---|---|---|---|---|---|---|---|---|---|
| | | | | | | | | $V_{CC}$ | |
| Propagation Delay Time | $t_{PLH}$ $t_{PHL}$ | A | Y | 1.3 | - | 13.0 | ns | 1.65 V to 1.95 V | - |
| | | | | 0.6 | - | 12.0 | | 2.3 V to 2.7 V | - |
| | | | | 0.5 | - | 11.0 | | 3.0 V to 3.6 V | - |
| | | | | 0.4 | - | 10.0 | | 4.5 V to 5.5 V | - |
| Power Dissipation Capacitance | $C_{PD}$ | - | - | - | 34 | - | pF | 3.3 V | f = 10 MHz, Ta = 25 °C |
| | | - | - | - | 38 | - | pF | 5.0 V | f = 10 MHz, Ta = 25 °C |

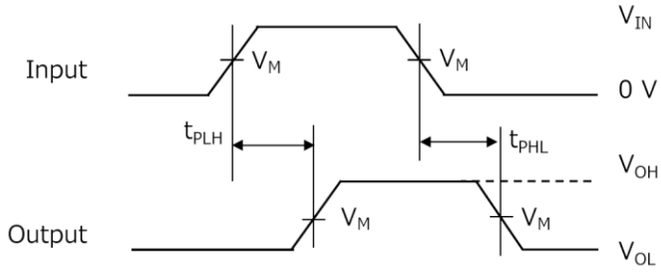
## Parameter Measurement Conditions




Measurement circuit for $t_{PLH}$ and $t_{PHL}$

| $V_{CC}$ | $V_{IN}$ | $V_M$ | $C_L$ (Note 1) | $R_L$ | tr/tf (Inputs) |
|---|---|---|---|---|---|
| 1.65 V to 1.95 V | $V_{CC}$ | 0.5 × $V_{CC}$ | 30 pF | 1k Ω | ≤ 2 ns |
| 2.3 V to 2.7 V | $V_{CC}$ | 0.5 × $V_{CC}$ | 30 pF | 500 Ω | ≤ 2 ns |
| 3.0 V to 3.6 V | 3.0 V | 1.5 V | 50 pF | 500 Ω | ≤ 2.5 ns |
| 4.5 V to 5.5 V | $V_{CC}$ | 0.5 × $V_{CC}$ | 50 pF | 500 Ω | ≤ 2.5 ns |

*(Note 1)* $C_L$ includes probe and test board capacitance.




Measurement Circuit and Timing Chart


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## Typical Performance Curves

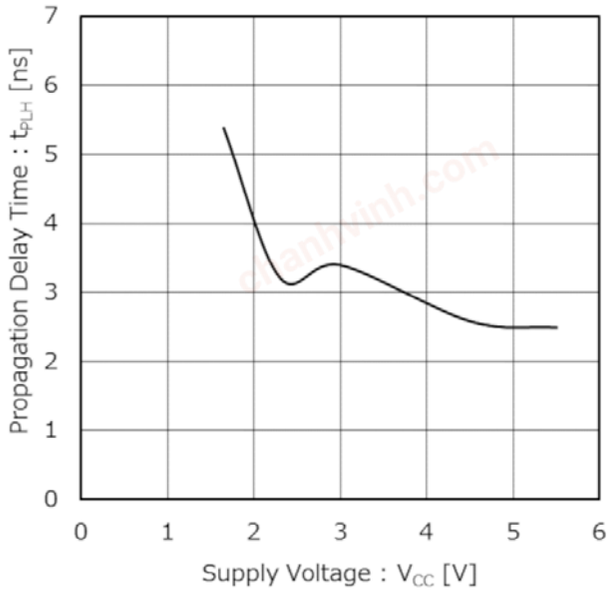



Figure 1. Propagation Delay Time: $t_{PLH}$ vs Supply Voltage: $V_{CC}$
(Ta = 25 °C)

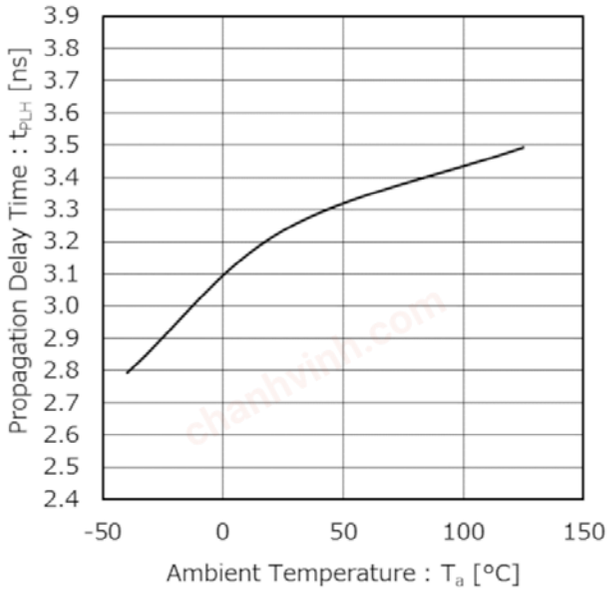



Figure 2. Propagation Delay Time: $t_{PLH}$ vs Ambient Temperature: Ta
($V_{CC}$ = 3.3 V)

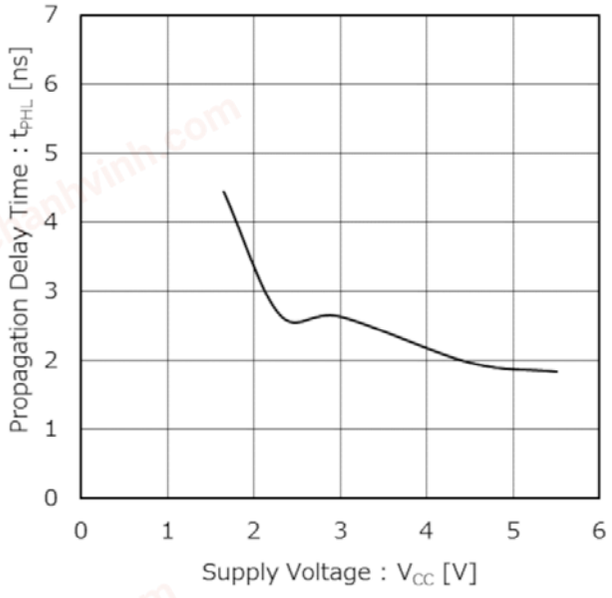



Figure 3. Propagation Delay Time: $t_{PHL}$ vs Supply Voltage: $V_{CC}$
(Ta = 25 °C)

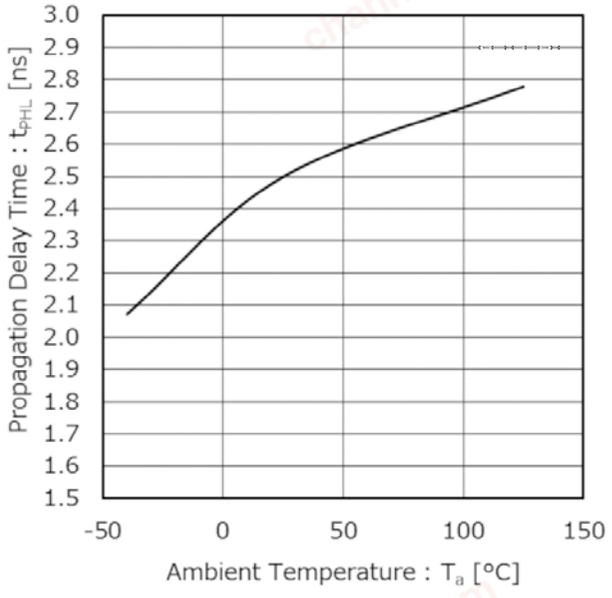



Figure 4. Propagation Delay Time: $t_{PHL}$ vs Ambient Temperature: Ta
($V_{CC}$ = 3.3 V)


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## Operational Notes

1. Reverse Connection of Power Supply
   Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines
   Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage
   Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern
   When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Recommended Operating Conditions
   The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. Inrush Current
   When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. Operation Under Strong Electromagnetic Field
   Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

8. Testing on Application Boards
   When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

9. Inter-pin Short and Mounting Errors
   Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

10. Unused Input Pins
    Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.


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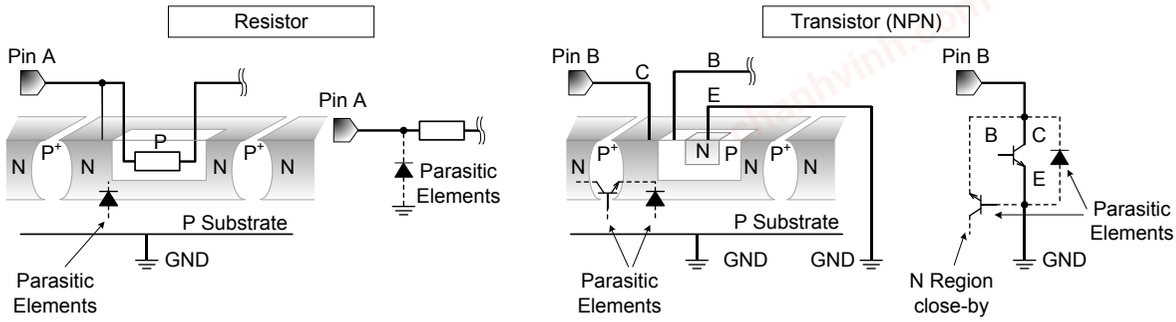
## Operational Notes – continued

**11.** Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.
When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these




diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

Example of Monolithic IC Structure

**12.** Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.


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## Ordering Information

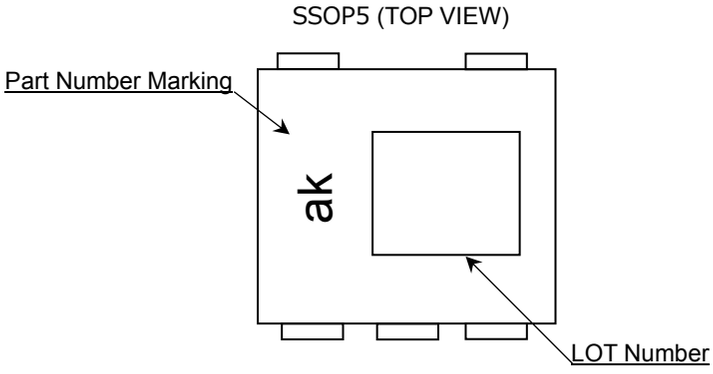
| B D 7 L S 3 4 G | - | C T L |
|---|---|---|

Package
G: SSOP5

Product Rank
C: for Automotive

Packaging and forming specification
TL: Embossed tape and reel

## Marking Diagram





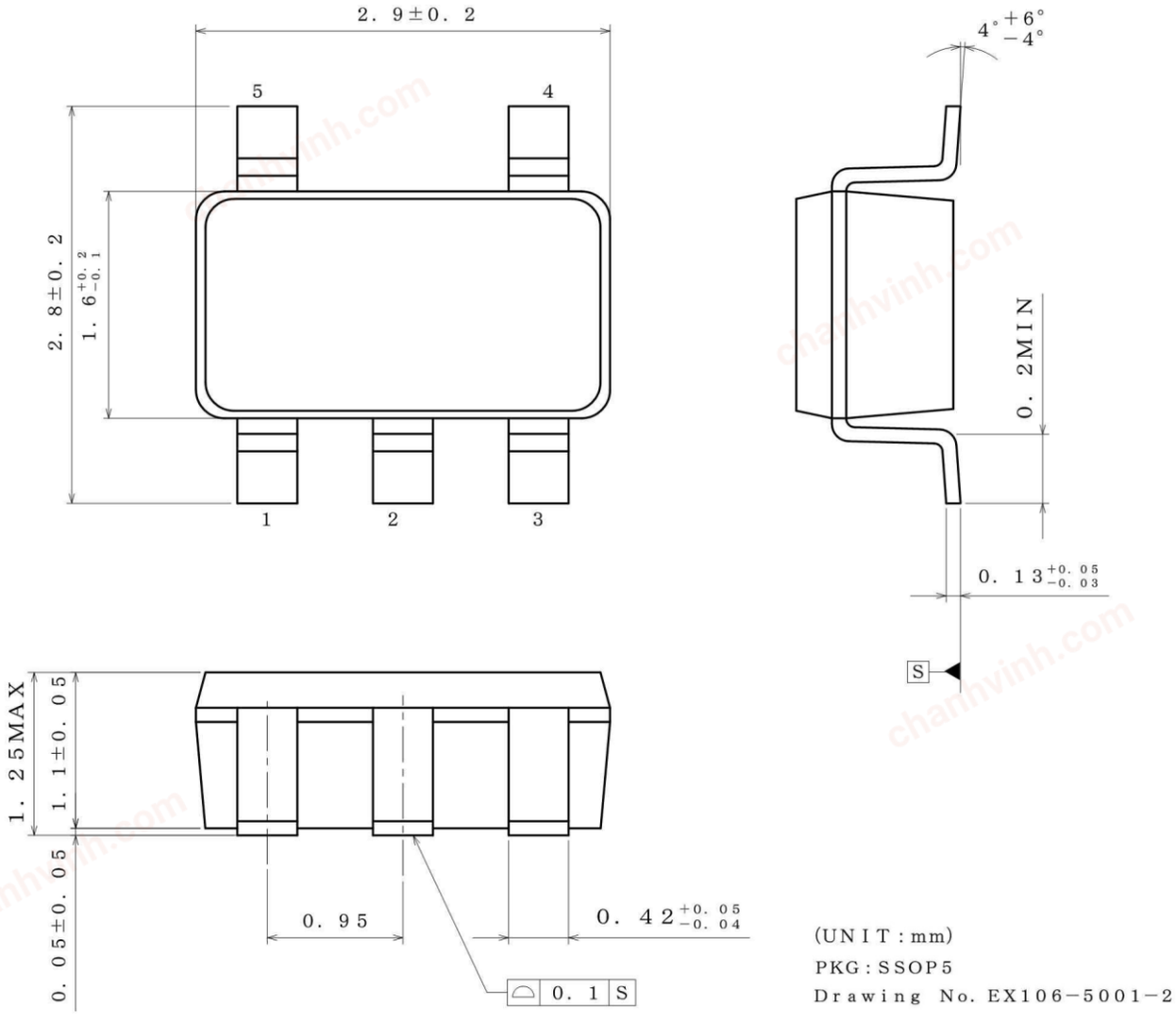
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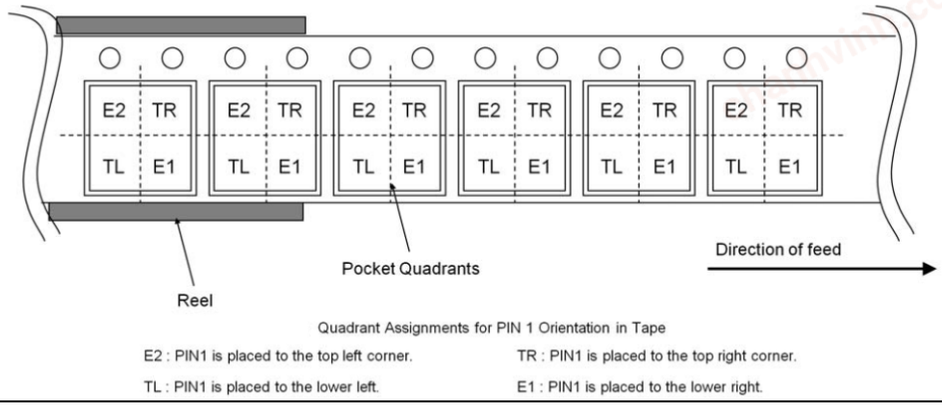


## Physical Dimension and Packing Information

| Package Name | SSOP5 |
|---|---|




| Packing Information | |
|---|---|
| Packing Form | Embossed carrier tape |
| Quantity | 3000 pcs |
| Direction of feed | TL |




Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner. TR : PIN1 is placed to the top right corner.

TL : PIN1 is placed to the lower left. E1 : PIN1 is placed to the lower right.


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## Revision History

| Date | Revision | Changes |
|---|---|---|
| 21.Apr.2020 | 001 | New Release |

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(Note1) Medical Equipment Classification of the Specific Applications

| JAPAN | USA | EU | CHINA |
|---|---|---|---|
| CLASSⅢ | CLASSⅢ | CLASSⅡb | CLASSⅢ |
| CLASSⅣ | | CLASSⅢ | |

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   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification


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## Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

## Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   - [a] the Products are exposed to sea winds or corrosive gases, including $Cl_2$, $H_2S$, $NH_3$, $SO_2$, and $NO_2$
   - [b] the temperature or humidity exceeds those recommended by ROHM
   - [c] the Products are exposed to direct sunshine or condensation
   - [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

## Precaution for Product Label

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